

IN THE SPECIFICATION

On page 2, after the Title, please insert:

-- This application is a divisional of U.S. Application Serial No. 10/141,447, filed May 8, 2002. --

IN THE CLAIMS

Please cancel claims 1-34, 40-44 and 50-62. Please add claims 63-67. For the Examiner's convenience, all currently pending claims have been reproduced below.

1-34. (Cancelled)

35. (Original) An integrated circuit comprising:

a stack comprising at least two semiconductor die, each of the semiconductor die being coupled together by a first adhesive, the first adhesive being curable at a first temperature; and

a substrate coupled to one of the at least two semiconductor die by a second adhesive, the second adhesive being curable at a second temperature lower than the first temperature.

36. (Original) The integrated circuit, as set forth in claim 35, wherein one of the at least two semiconductor die is thicker than a second of the at least two semiconductor die.

37. (Original) The integrated circuit, as set forth in claim 35, wherein the topside surface area of one of the at least two semiconductor die is less than the topside surface area of a second of the at least two semiconductor die.

38. (Original) The integrated circuit, as set forth in claim 35, wherein the stack of at least two semiconductor die is configured such that the stack comprises a shingle stack.

39. (Original) The integrated circuit, as set forth in claim 35, wherein at least one of the at least two semiconductor die comprises a memory die.

40-44. (Cancelled)

45. (Original) An integrated circuit comprising a stack of at least two semiconductor die, each of the die being coupled to an adjacent die in the stack by a respective layer of adhesive prior to the stack being coupled to a packaging substrate.

46. (Original) The integrated circuit, as set forth in claim 45, wherein one of the at least two semiconductor die is thicker than a second of the at least two semiconductor die.

47. (Original) The integrated circuit, as set forth in claim 45, wherein the topside surface area of one of the at least two semiconductor die is less than the topside surface area of a second of the at least two semiconductor die.

48. (Original) The integrated circuit, as set forth in claim 45, wherein the stack of at least two semiconductor die is configured such that the stack comprises a shingle stack.

49. (Original) The integrated circuit, as set forth in claim 45, wherein at least one of the at least two semiconductor die comprises a memory die.

50-62. (Cancelled)

63. (New) An integrate circuit package comprising:

a substrate; and

a die stack coupled to the substrate, wherein the die stack comprises at least two semiconductor die coupled together and wherein the dies stack is formed prior to being coupled to the substrate.

64. (New) The integrated circuit package, as set forth in claim 63, wherein one of the at least two semiconductor die is thicker than a second of the at least two semiconductor die.

65. (New) The integrated circuit package, as set forth in claim 63, wherein the topside surface area of one of the at least two semiconductor die is less than the topside surface area of a second of the at least two semiconductor die.

66. (New) The integrated circuit package, as set forth in claim 63, wherein the stack of at least two semiconductor die is configured such that the stack comprises a shingle stack.

67. (New) The integrated circuit package, as set forth in claim 63, wherein at least one of the at least two semiconductor die comprises a memory die.

Conclusion

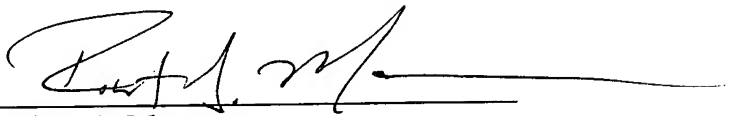
In view of the amendments set forth above, Applicants respectfully request consideration of present claims 35-39, 45-49 and 63-67. If the Examiner believes that a telephonic interview will help speed this application toward issuance, the Examiner is invited to contact the undersigned at the telephone number listed below.

General Authorization for Payment of Fees and Extensions of Time

In accordance with 37 C.F.R. § 1.136, Applicants hereby provide a general authorization to treat this and any future reply requiring an extension of time as incorporating a request therefore. Furthermore, Applicants authorize the Commissioner to charge the appropriate fee for the additional claims and for any extension of time to Deposit Account No. 13-3092; Order No. MICS:0078--1/FLE (01-0752.01).

Respectfully submitted,

Date: September 25, 2003


Robert A. Manware
Reg. No. 48,758
Fletcher Yoder
P.O. Box 692289
Houston, Texas 77269-2289
(281) 970-4545